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Aehr Test Systems to Showcase Next Generation FOX-XP™ Test and Burn-in System at the 2016 International Test Conference in Fort Worth November 15-17

Fremont, CA (November 14, 2016) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced that it will be showcasing its FOX-XP System, its next generation multi-wafer test and burn-in system for high volume production and early failure rate (EFR) test at the 2016 International Test Conference (ITC) taking place November 15-17 in Fort Worth, Texas at the Fort Worth Convention Center (Booth #318).

Aehr Test's FOX-XP system is capable of functional test and burn-in/cycling of flash memories, microcontrollers, sensors, optical devices, laser diodes, VCSELs, LEDs and other leading-edge ICs in wafer form before they are assembled into multi-die packages or other applications where known good die are critical. These end applications can span enterprise solid state drives, automotive devices, highly valuable mobile applications, communications and mission critical integrated circuits and sensors.

The key features of the new FOX-XP test cell that contribute to the cost-effectiveness of the solution include the ability to provide up to 2,048 "Universal Channels" per wafer, which allows the system to test all the devices on the wafer in parallel. The new "Universal Channel" architecture allows any channel to be any function (I/O, Device Power Supply (DPS) or Per-pin Precision Measurement Unit (PPMU)). This enhanced architecture now allows customers to perform per pin parametric testing, more extensive digital pattern test with deeper data stimulus / capture memory (32M per pin), and deeper scan (768M) optimized for BIST/DFT testing.

A single FOX-XP test system may be configured with up to 18 slots of wafer test resources enabling up to 18 wafers to be tested simultaneously. It also includes Aehr's proprietary WaferPak full wafer contactor, which enables meeting the very high pin count and small pad size and pad pitch requirements of today's devices, and Aehr's high performance thermal chucks that enable managing the temperature of the high power density of the devices on the wafer. The footprint of the 18 wafer test system is similar to the footprint of typical semiconductor Automatic Test Equipment (ATE) that can only test one wafer at a time.

With the highest wafer throughput available in the ATE industry, the flexibility of Aehr Test's new "Universal Channel" architecture, and the ability to perform both functional pattern verification and parametric testing at full-wafer parallel test, the FOX-XP system provides a highly differentiated solution from competitive alternatives.

The FOX-XP system utilizes Aehr Test's FOX WaferPak contactor, which provides a cost effective solution for making full wafer electrical die contact in a multi-wafer environment. Aehr Test's WaferPak contactors contain up to tens of thousands of probes to contact all die simultaneously on wafers and substrates up to 300mm.

Aehr Test will also be showcasing the ABTS family of products, which is based on a state-of-the-art hardware and software platform that is designed to address not only today's devices, but also future devices for many years to come. It can test and burn-in both logic and memory devices and includes resources for high pin-count devices and configurations for high-power and low-power applications. ABTS systems can be configured with up to 72 burn-in boards, up to 320 I/O channels, 32M of test vector memory per channel and up to 16 independent device power supplies. The ABTS system can be configured with a scalable cost-effective individual device temperature control solution for up to 64 devices per burn-in board and up to 75 watts per device or more. Individual temperature control enables high-power devices with a broad range of power dissipation to be burned-in simultaneously in a single burn-in chamber while maintaining a precise device temperature. The ABTS system also uses N+1 redundancy technology for many key components in the system to maximize system uptime.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX families of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both lower-power and higher-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at www.aehr.com.

Safe Harbor Statement

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding Aehr Test's expectations, beliefs, intentions or strategies regarding the FOX products, including statements regarding future market opportunities and conditions, expected product shipment dates and customer orders or commitments. These risks and uncertainties include, without limitation, acceptance by customers of the FOX and WaferPak contactor technologies, acceptance by customers of the FOX-XP system, WaferPak Aligner and WaferPak contactors shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described, as well as general market conditions, customer demand and acceptance of Aehr Test's products and Aehr Test's ability to execute on its business strategy. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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